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solder[1,noun] **Go**
solder[2,verb]

Main Entry: **1solder** ⓘ

Pronunciation: 'sä-d&r, 'so-, British also 'säl-d&r, 'sol-

Function: *noun*

Etymology: Middle English *soudure*, from Middle French, from *souder* to solder, from Latin *solidare* to make solid, from *solidus* solid

1 : a metal or metallic alloy used when melted to join metallic surfaces; *especially* : an alloy of lead and tin so used
2 : something that unites

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PAD

A. The portion of a conductive pattern on a solid-state electronic device for making external connection thereto. B. The portion of a conductive pattern on a chip or a printed circuit board designed for mounting or attaching a substrate or solid-state active electronic device. See also bonding pad, die bond, etc.

FLIP-CHIP

A term which describes the situation wherein a semiconductor device which has all terminations on one side thereof in the form of bump contacts, has a passivated surface, and has been flipped over and attached to a matching substrate.